

IEEE Transactions on Intelligent Transportation Systems

Special Issue on "Applications of Mechatronic and Embedded Systems in Intelligent Transportation Systems"

Scope: Mechanical and electrical systems show an increasing integration of mechanics with electronics and information processing. This integration is between the components (hardware) and the information-driven functions (software), resulting in integrated systems called mechatronic systems. The development of mechatronic systems involves finding an optimal balance between the basic mechanical structure, sensor and actuators, automatic digital information processing and control in which embedded systems play a key role.

We aim to provide a collage of high-quality papers presenting technologies, methodologies and, particularly, applications for mechatronic and embedded systems in any aspect of Intelligent Transportation Systems, including both established and state-of-the-art solutions, and showcase emerging innovative ideas and technologies. Originated within the activities of the Symposium “Mechatronic & Embedded Technologies in Intelligent Transportation Systems” at the *12th IEEE/ASME International Conference on Mechatronic and Embedded Systems and Applications - MESA 2016* held in Auckland (New Zealand) from August 29-31, this special issue is open to the entire international research community without the necessity of conference participation. Papers suitable for this issue should focus on topics including, but not limited to:

- Automatic Vehicle Localization (AVL)
- Automatic Vehicle Monitoring (AVM)
- Autonomous vehicles
- Automotive systems
- Driver assistance systems
- Environment perception (image, radar, Lidar signal processing)
- Human Machine Interface (HMI)
- Intelligent Vehicle Software Infrastructure
- Safety & security systems
- Systems interoperability and integration
- Technologies for ITS user services
- Traffic and communications networks
- Traffic modeling, planning, simulation
- Transportation management systems
- Vehicular electronics

Guest Editors (in alphabetical order)

Massimo Bertozzi

Università di Parma/VisLab

bertozzi@ce.unipr.it

Bo Chen

Michigan Technological University

bochen@mtu.edu

Primo Zingaretti

Università Politecnica delle Marche

p.zingaretti@univpm.it

Key Dates

The intended timeline for the overall publication process of this special issue is:

Special issue article type becomes available in EES: October 10, 2016

Submission deadline of full papers: January 15, 2017

Feedback from first-round reviews: March 10, 2017

Feedback from second-round reviews: June 9, 2017

Revised manuscripts due: July 28, 2017

Notification of final decision: September 15, 2017

Final manuscripts due: October 13, 2017

Publication: November 2017

Submission via EES

All papers should be submitted through Manuscript Central at <http://mc.manuscriptcentral.com/t-its>. While submitting a paper to the special issue, please choose the article type “Applications of Mechatronic and Embedded Systems in Intelligent Transportation Systems” otherwise your submission will be handled as a regular manuscript. All submissions will go through the journal’s standard peer review process. Criteria for acceptance include originality, contribution, and scientific merit. For author guidelines please visit <http://sites.ieee.org/itss/publications/transactions/authors-information/>.